



## Advanced Product Change Notification

202104008A : SOT552-1 Transfer from ATP-1 to ASEN

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** May 24, 2021

Here is your personalized notification about a NXP general announcement.  
For detailed information we invite you to view this notification online

### Management summary

Due to the low volume of SOT552-1 running at ATP-1, assembly will transfer from ATP-1 to ASEN.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

Due to the low volume of SOT552-1 running at ATP-1, assembly will transfer from ATP-1 to ASEN. The material set will change to the ASEN standard material set which includes a roughened (RT) leadframe. This leadframe is a quality improvement which provides superior delamination performance after customer's SMT. It should be noted that orderable part numbers will change to reflect the use of SBB (Static Barrier Bag) needed for the RT lead frame.

- Please contact Frans Voogt and Dennis Dill at the following contact points if there are questions:  
Frans.voogt@nxp.com / Dennis.dill@nxp.com

### Reason

Due to the low volumes on SOT552-1 at ATP-1, assembly will transfer from ATP-1 to ASEN.

### Identification of Affected Products

Product identification does not change

### Product Availability

### Sample Information

Samples are available upon request

### Production

Planned first shipment Sep 06, 2021

### Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

**Data Sheet Revision**

A new datasheet will be issued

**Disposition of Old Products**

Existing inventory will be shipped until depleted

**Timing and Logistics**

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The Self Qualification Report will be ready on Jul 09, 2021.

The Final PCN is planned to be issued on: Jul 09, 2021.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jun 23, 2021.

**Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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<b>Position</b>	Quality Engineer
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NXP Quality Management Team.

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
PCF85263ATT1/AJ	935304461118	PCF85263ATT1/A	Tiny RTC with Batt switch TSSOP10	(T)SSOP10	SOT552-1	RFS	No	BLC6
PCF85263ATT1/AZ	935304461431	PCF85263ATT1/A	Tiny RTC with Batt switch TSSOP10	(T)SSOP10	SOT552-1	DEV	No	BLC6
PCF85363ATT1/AJ	935304752118	PCF85363ATT1/A	Tiny RTC Bat switch RAM I2C TSSOP10	(T)SSOP10	SOT552-1	RFS	No	BLC6
PCF85363ATT1/AZ	935304752431	PCF85363ATT1/A	Tiny RTC Bat switch RAM I2C TSSOP10	(T)SSOP10	SOT552-1	DEV	No	BLC6
PCA9527DP,118	935289105118	PCA9527DP	3channel bidirectional bus extender	(T)SSOP10	SOT552-1	RFS	No	BLC6
PCA9527DPZ	935289105431	PCA9527DP	3channel bidirectional bus extender	(T)SSOP10	SOT552-1	DEV	No	BLC6
PCA9537DP,118	935277495118	PCA9537DP	PCA9537	(T)SSOP10	SOT552-1	RFS	No	BLC6
PCA9537DPZ	935277495431	PCA9537DP	PCA9537	(T)SSOP10	SOT552-1	DEV	No	BLC6
PCA9614DP,118	935298545118	PCA9614DP	2-ch multipoint Fm+ dl2C-bus buffer	(T)SSOP10	SOT552-1	RFS	No	BLC6
PCA9614DPZ	935298545431	PCA9614DP	2-ch multipoint Fm+ dl2C-bus buffer	(T)SSOP10	SOT552-1	DEV	No	BLC6
PCA9615DPJ	935302505118	PCA9615DP	2-ch mp hot swap Fm+ dl2C-bus buffe	(T)SSOP10	SOT552-1	RFS	No	BLC6
PCA9615DPZ	935302505431	PCA9615DP	2-ch mp hot swap Fm+ dl2C-bus buffe	(T)SSOP10	SOT552-1	DEV	No	BLC6
PCA9632DP2,118	935286528118	PCA9632DP2	PCA9632	(T)SSOP10	SOT552-1	RFS	No	BLC6
PCA9632DP2Z	935286528431	PCA9632DP2	PCA9632	(T)SSOP10	SOT552-1	DEV	No	BLC6